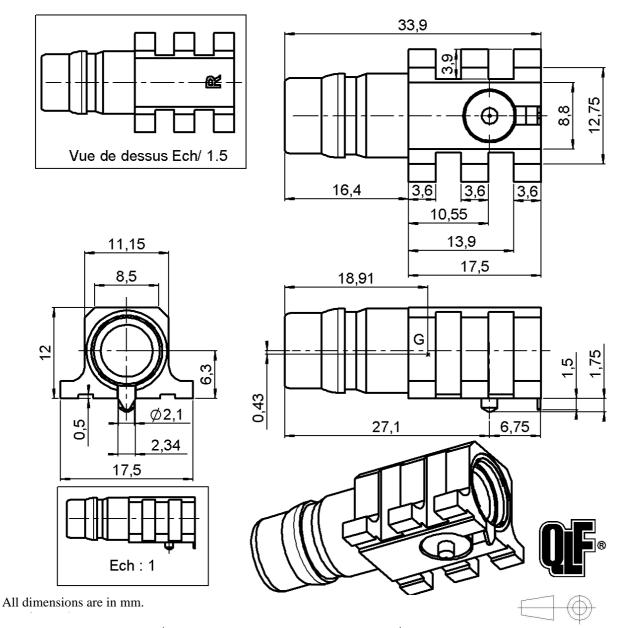
REEL 100

R164.682.803

Series : QN



COMPONENTS	MATERIALS	PLATINGS (μm)	
BODY CENTER CONTACT OUTER CONTACT INSULATOR	BRASS BERYLLIUM COPPER PTFE	GBR 2 GOLD 1.3 OVER COPPER 2.5	
GASKET OTHERS PARTS	BRASS	GOLD 0.8 OVER COPPER 0.5	
-	-	-	
-	-	-	

Issue: 0420 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



REEL 100

5000 M Ω mini

R164.682.803

Series: QN

PACKAGING

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance $\mathbf{50}$ Ω Frequency $\mathbf{0-6*}$ GHz

VSWR 1.05 + 0.025 x F(GHz) Maxi

Insertion loss 1.03 + 0.023 \times 1 (GHz) Maxi + 0.048 $\sqrt{F(GHz)}$ dB Maxi

RF leakage - (**90 - F(GHz)) dB Maxi Voltage rating 500 Veff Maxi Dielectric withstanding voltage 1500 Veff mini

ENVIRONMENTAL

Operating temperature -55/+125° ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

*usable 0-11GHz(ligne adaptée seulement)
**RF Leakage : -80dB min 3<F<6GHz
***PIM3: -112 dBm (2 x 20W at 1.8GHz)

MECHANICAL CHARACTERISTICS

Center contact retention

Insulation resistance

Axial force – Mating end
Axial force – Opposite end
Torque

18 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **21.100** g

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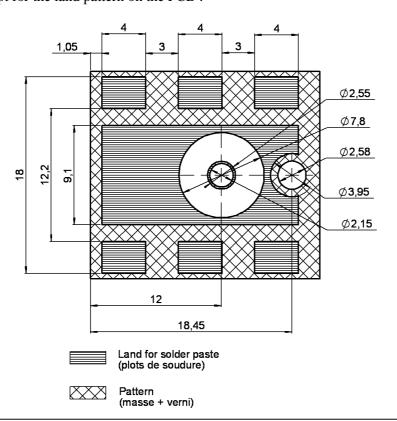
RIGHT ANGLE SMT RECEPTACLE

Series : QN

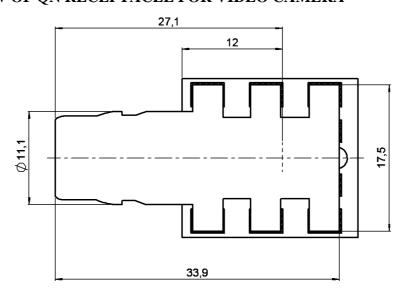
REEL 100

ON SERIES - INFORMATIONS

Coplanar line : pattern and signal are on the same side . Thickness of PCB : .063(1.6mm) The material of PCB is the epoxy resin of glass fabrics bacs . (Er = 4.8) . The solder resist should be printed exept for the land pattern on the PCB .



SHADOW OF QN RECEPTACLE FOR VIDEO CAMERA



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REEL 100

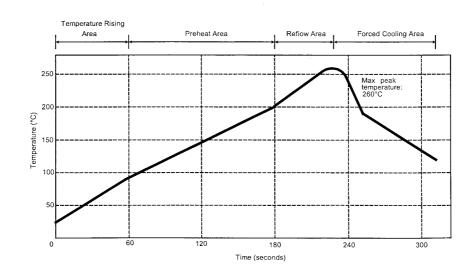
R164.682.803

Series: QN

SOLDER PROCEDURE

- Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application.
 We recommend a low residue flux.
 We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
 Video camera is preferred to check the positioning of the compnent. Adhesive agents are forbidden on the receptacle.
- 3. Soldering by infra-red reflow.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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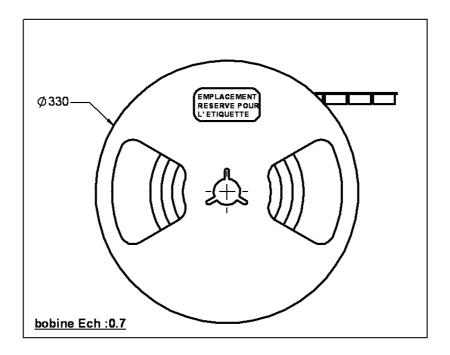
necessary.

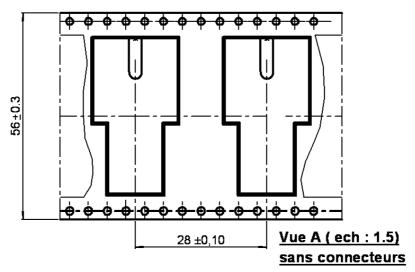


REEL 100

R164.682.803

Series : **QN**





Issue: 0420 B

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